



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

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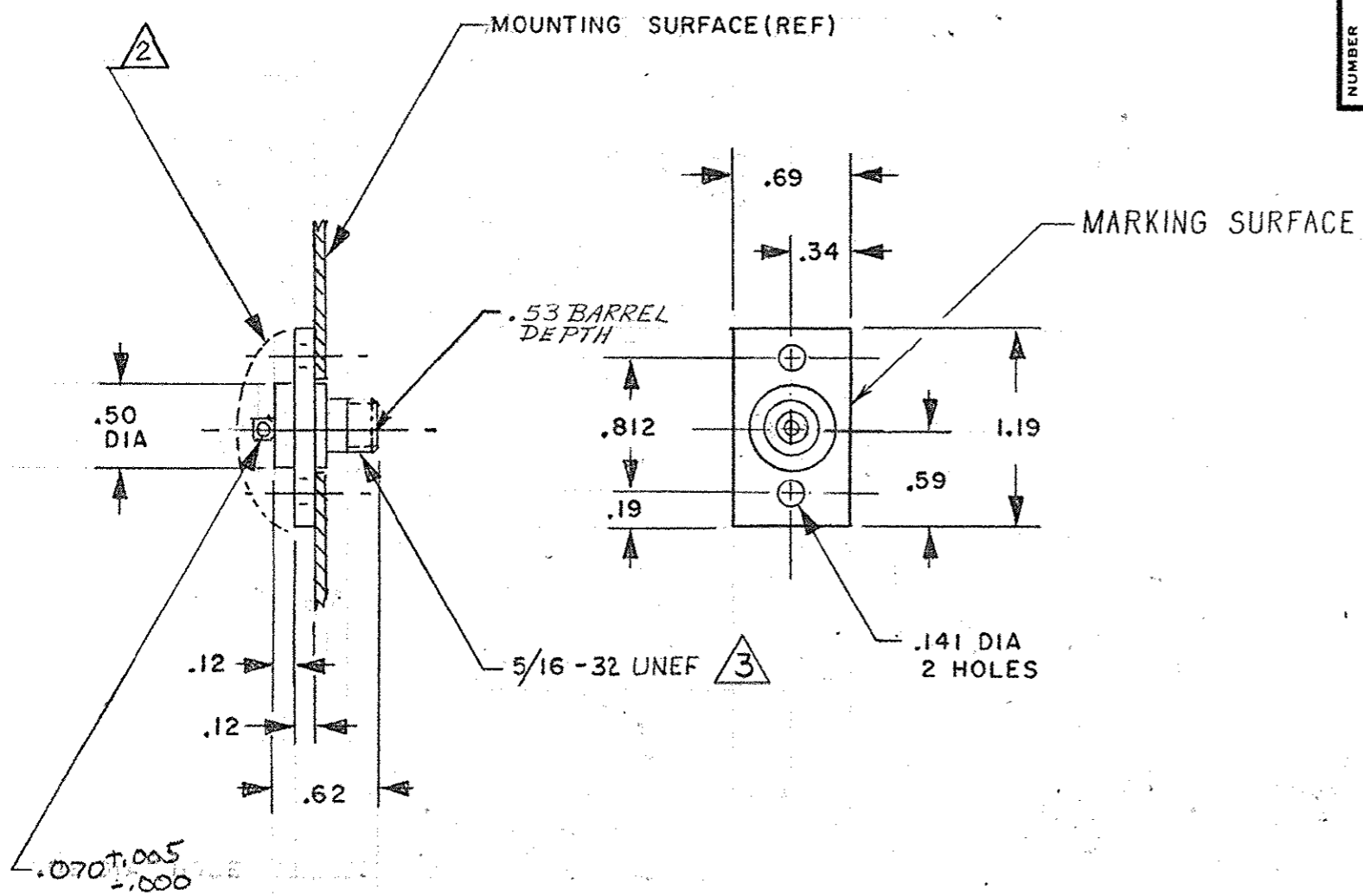
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NUMBER 846349

REVISIONS				
ZONE	SYM	DESCRIPTION	DATE	APPROVAL
	-	WAS SK-20518A & SD 20534D		
	A	ADDED .53 BARREL DEPTH	8-19-68	Ken K
	B	REV. MAT. & FINISH	10-14-70	Ken K
	C	REVISED PER ECN 4349	D.S. 5-22-74	M.S.
	D	ADDED MARKING NOTE	KH 8-23-76	M.S.
	E	REV. PER E.C.N 8595	AG 1-30-79	M.S.
	F	REV PER ECN 5-3960	9/20/87	R8
✓	G	REV PER 0600-1103-93	CT 3-94	DW
	H	REV PER 0414-0192-05	1-06	PY



1. RECEPTACLE TO MATE WITH AMP LGH 1/2L LEAD ASSEMBLY, AVAILABLE SEPARATELY. WHEN MATING LEAD ASSEMBLY WITH RECEPTACLE, APPLY SILICONE GREASE PER 830800 INSTRUCTIONS.
2. PROTECT THIS END, IF NOT ENCAPSULATED, AGAINST VOLTAGE BREAKDOWN, IF BULKHEAD &/OR MOUNTING HARDWARE IS METALIC &/ AT GROUND POTENTIAL
3. PER FEDERAL STANDARD H-28 3 WIRE METHOD. DIMENSION OVER WIRES TO BE: .307-.318.

5-846349-1	TIN PLATED PIN
846349-1	TIN-LEAD PLATED PIN

REQD	SIZE	ITEM	PART NO	DESCRIPTION	MATL	MATL SPEC
-1				LIST OF MATERIAL		

UNLESS OTHERWISE SPECIFIED				SIGNATURE		DATE		NAME	
DIMENSIONS ARE IN INCHES				<i>[Signature]</i>		9-9		FLANGED RECEPTACLE ASSY	
TOLERANCES ON FRACTIONS				CHK		66		LGH-1/2L	
XX ± .03				DSGN ENGR				(FOR BULKHEAD APPLICATION)	
XXX ± .015				APPD		9-9		AMP INCORPORATED	
MATERIAL				<i>[Signature]</i>		66		CAPITRON DIVISION	
MOLDED GLASS EPOXY				HEAT TREAT		<i>[Signature]</i>		ELIZABETHTOWN	
				FINISH		BLACK		PENNSYLVANIA	
NEXT ASSY		USED ON		NEXT ASSY		FINAL ASSY		LOC PRINT DIST	
APPLICATION		QTY REQD		SCALE 1/1		CODE IDENTIFICATION		SIZE NUMBER	
						00779		B 846349	
				WT		CALC ACTUAL CONTRACT NO		SHEET 1 OF 1	

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